



Material Content Data Sheet



Sales Product Name	BB 831 E7904			Issued		29. August 2013		
MA#	MA000312380							
Package	PG-SOD323-2-1			Weight*		4.46 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.003	0.07		672	
	non noble metal	arsenic	7440-38-2	0.000	0.00		7	
	inorganic material	silicon	7440-21-3	0.026	0.57	0.64	5740	6419
leadframe	non noble metal	chromium	7440-47-3	0.004	0.09		938	
	inorganic material	silicon	7440-21-3	0.000	0.01		63	
	non noble metal	titanium	7440-32-6	0.001	0.03		313	
	non noble metal	copper	7440-50-8	1.387	31.13	31.26	311331	312645
wire	noble metal	gold	7440-57-5	0.007	0.15	0.15	1500	1500
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.032	0.72		7186	
	organic material	carbon black	1333-86-4	0.032	0.72		7186	
	plastics	brominated resin	-	0.079	1.76		17638	
	plastics	epoxy resin	-	0.731	16.40		163964	
	inorganic material	silicondioxide	60676-86-0	2.037	45.73	65.33	457270	653244
leadfinish	non noble metal	tin	7440-31-5	0.076	1.71	1.71	17091	17091
plating	noble metal	silver	7440-22-4	0.041	0.91	0.91	9101	9101
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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